Product Change Notification: JPZA-16CPDL798

Date:

25-Sep-2026

Product Category:

CAN Controller

Notification Subject:

CCB 8550 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for MCP2518FDT-E/QBB and MCP2518FDT-H/QBB catalog part numbers (CPN) available in 14L VDFN (3x4.5mm) package at MMT assembly site.

Affected CPNs:

JPZA-16CPDL798_Affected_CPN_09252026.pdf
JPZA-16CPDL798_Affected_CPN_09252026.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for MCP2518FDT-E/QBB and MCP2518FDT-H/QBB catalog part numbers (CPN) available in 14L VDFN (3x4.5mm) package at MMT assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change
Assembly Site	Microchip Technology Thailand (Branch) (MMT)	Microchip Technology Thailand (Branch) (MMT)	No
Wire Material	Au	CuPdAu	Yes
Die Attach Material	8006NS	8006NS	No

Molding Compound Material	G700LTD	G700LTD	No
Lead-Frame Material	A194	A194	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new wire material at MMT assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 10 December 2026 (date code: 2650)

Note Below EFSD: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	September 2026					>	December 2026				
Work Week	36	37	38	39	40		49	50	51	52	53
Qual Report Availability				**x**							
Final PCN Issue Date				**x**							
Estimated Implementation Date								x			

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.
Note: This is a qualification by similarity (QBS) to CCB# 6533 and 7764.001

Revision History: September 25, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance

regarding the material content of the applicable product.

Attachments:

PCN_JPZA-16CPDL798 Qual Report 6533.pdf
PCN_JPZA-16CPDL798 Qual Report 7764.001.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

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If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN):

MCP2518FDT-E/QBB

MCP2518FDT-H/QBB



Qualification Report Summary

RELIABILITY LABORATORY

PCN #: JPZA-16CPDL798

Date

October 3, 2024

Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for MCP2518FDT-E/QBB and MCP2518FDT-H/QBB catalog part numbers (CPN) available in 14L VDFN (3x4.5mm) package at MMT assembly site. This is Q100 Grade 0 qualification.

PACKAGE QUALIFICATION REPORT

Purpose:

Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for MCP2518FDT-E/QBB and MCP2518FDT-H/QBB catalog part numbers (CPN) available in 14L VDFN (3x4.5mm) package at MMT assembly site. This is Q100 Grade 0 qualification.

CN:	E000209064
QUAL ID:	R2400189
QUAL ID Rev.:	A
MP CODE:	TAGD1JQBBVA1
Part No.:	MCP2518FDT-H/QBBVAO
Bonding No.:	BD-001709 Rev. 01
CCB No.:	6533

Lead Frame

Paddle Size:	75 x 169 mils
Material:	A194
DAP Surface Prep:	Ag
Process:	Etched
Lead Lock:	Yes
Part Number:	10101414
Lead Plating:	Matte Sn

Bond Wire

Wire:	Au wire

Die Attach Material

Epoxy:	8006NS

Mold Compound

Mold Compound:	G700LTD

Package

Type:	14L VDFN-WFS
Package Size:	3 x 4.5 mm

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MMT-244101783.000	TC08924219232.110	2402K0Q
MMT-244101784.000	TC08924219232.110	2402Q0J
MMT-244101785.000	TC08924219232.110	2402Q28

Result: **Pass**

Conclusion:

14L VDFN (3x4.5 mm) assembled by MMT pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Precondition Prior Perform Reliability Tests (At MSL Level 1)	**Electrical Test:** +25°C, 85°C, 125°C and 150°C **System:** J750	JESD22-A113 JIP/IPC/JEDEC J-STD-020E	693(0)	0/693	Pass	Good Devices
	Bake 150°C, 24 hrs. **System:** CHINEE			693		
	85°C/85%RH Moisture Soak 168 hrs. **System:** TABAI ESPEC Model PR-3SPH			693		
	3x Convection-Reflow 265°C max **System:** Vitronics Soltec MR1243			693		
	Electrical Test: +25°C, 85°C, 125°C and 150°C **System:** J750		693(0)	0/693	Pass	
Temp Cycle	**Stress Condition:** -55°C to +150°C, 1500 Cycles **System:** TABAI ESPEC TSA-70H	JESD22-A104		0/231		Parts had been pre-conditioned at 260°C 77 units / lot
	Electrical Test: +85°C,125°C and 150°C **System:** J750		231(0)	0/231	Pass	
UNBIASED-HAST	**Stress Condition:** +130°C/85%RH, 96 hrs. **System:** HAST 6000X	JESD22-A118		0/231		Parts had been pre-conditioned at 260°C 77 units / lot
	Electrical Test: +25°C **System:** J750		231(0)	0/231	Pass	
HAST	**Stress Condition:** +130°C/85%RH, 96 hrs. Bias Volt: 5.5 Volts **System:** HAST 6000X	JESD22-A110		0/231		Parts had been pre-conditioned at 260°C 77 units / lot
	Electrical Test: +25°C, 85°C, 125°C and 150°C **System:** J750		231(0)	0/231	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
High Temperature Storage Life	**Stress Condition:** Bake 175°C, 1000 hrs. **System:** TPS Bake Oven	JESD22-A103		0/45		45 units
	Electrical Test: +25°C, 85°C, 125°C and 150°C **System:** J750		45(0)	0/45	Pass	
Bond Strength Data Assembly	Wire Pull (>2.50 grams)	Mil. Std. 883-2011	30(0) Wires	0/30	Pass	
	Bond Shear (>15.00 grams)	CDF-AEC-Q100-001	30(0) bonds	0/30	Pass	



Qualification Report Summary

RELIABILITY LABORATORY

PCN #: JPZA-16CPDL798

Date

June 10, 2026

Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for MCP2518FDT-E/QBB and MCP2518FDT-H/QBB catalog part numbers (CPN) available in 14L VDFN (3x4.5mm) package at MMT assembly site.

PACKAGE QUALIFICATION REPORT

Purpose:

Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for MCP2518FDT-E/QBB and MCP2518FDT-H/QBB catalog part numbers (CPN) available in 14L VDFN (3x4.5mm) package at MMT assembly site.

CN:	E000287245
QUAL ID:	R2501391
QUAL ID Rev.:	A
MP CODE:	ZA702YS8BD00
Part No.:	MCP16502TAD-E/S8B
Assembly Shipping	
Media (T/R, Tube/Tray):	T/R
Base Quantity	
Multiple (BQM):	8000
Bonding No.:	BD-000569 / Rev-05
CCB No.:	7764.001

Lead Frame

Paddle Size:	114 x 114
Material:	C194
DAP Surface Prep:	Ag ring plated DAP
Treatment:	BOT
Process:	Etched
Lead Lock:	YES
Part Number:	10103203
Lead Plating:	Ag plated

Bond Wire

Wire:	CuPdAu wire

Die Attach Material

Epoxy:	8006NS
Conductive:	No

Mold Compound

Mold Compound:	G700LTD

Package

PKG Type:	VQFN
Pin/Ball Count:	32L
PKG Width/Size:	5x5 mm

Manufacturing Information

Assembly Lot No.
MMT-262601100.000
MMT-262601235.000
MMT-262700399.000

Result: **Pass**

Conclusion:

Qualification of ZA702 mask / MCP16502TAD-E/S8B product / CuPdAu wire in 32L VQFN 5x5 mm package at MMT site is qualified for MSL3 at 260ºC as per JEDEC J-STD-020 standard and is passed in accordance to Specified JEDEC and Mil Standards

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Moisture Soak Precondition Prior to Stresses	**MSL3:** 150°C 24 hours Bake, 192 hours Moisture Soak at 30°C/60%RH, 3x Reflow at 260°C **Electrical Test:** 25°C and 125°C **Tester:** ETS88	JESD22-A113 , JEDEC J-STD-020	231 units each lot / 3 lots	0/231, 0/231, 0/231	Pass	
High Temp Storage	175°C / 500 hours **Electrical Test:** 25°C and 125°C **Tester:** ETS88	JESD22-A103	45 units each lot / 3 lots	0/45, 0/45, 0/45	Pass	
Temperature Cycling 1000 Cycles	-55°C / +150°C Air to Air / 1000 Cycles **Electrical Test:** 25°C and 125°C **Tester:** ETS88	JESD22-A104	77 units each lot / 3 lots	0/77, 0/77, 0/77	Pass	
	WBP			0/3, 0/3, 0/3	Pass	
	WBS			0/3, 0/3, 0/3	Pass	
Temperature Cycling 2000 Cycles	-55°C / +150°C Air to Air / 2000 Cycles **Electrical Test:** 25°C and 125°C **Tester:** ETS88	JESD22-A104	77 units each lot / 3 lots	0/77, 0/77, 0/77	Pass	
	WBP			0/3, 0/3, 0/3	Pass	
	WBS			0/3, 0/3, 0/3	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Biased HAST 96 hours	+130°C / 85%RH / 96 hours / Bias Voltage: 5.5V **Electrical Test:** 25°C and 125°C **Tester:** ETS88	JESD22-A110	77 units each lot / 3 lots	0/77, 0/77, 0/77	Pass	
	WBP			0/3, 0/3, 0/3	Pass	
	WBS			0/3, 0/3, 0/3	Pass	
Biased HAST 192 hours	+130°C / 85%RH / 192 hours / Bias Voltage: 5.5V **Electrical Test:** 25°C and 125°C **Tester:** ETS88	JESD22-A110	77 units each lot / 3 lots	0/77, 0/77, 0/77	Pass	
	WBP			0/3, 0/3, 0/3	Pass	
	WBS			0/3, 0/3, 0/3	Pass	
Unbiased HAST	+130°C / 85%RH / 96 hours **Electrical Test:** 25°C **Tester:** ETS88	JESD22-A118	77 units each lot / 3 lots	0/77, 0/77, 0/77	Pass	
Solderability (0 Hr) Method 1: Dip and Look	Pb-free 8 hours Steam age. Dip at 245°C, 100% leads >95% lead coverage	J-STD-002 / JESD22B-102	22 units / 1 lot	0/22	Pass	
Physical Dimension (0Hr)	Within package diagram dimension	JESD22 B100 and B108	10 units each lot / 3 lots	0/30	Pass	
Wire Pull	Bond Strength Data Assembly	Mil. Std. 883-2011	5 units / 1 lot	0/5	Pass	
Bond Shear	Bond Strength Data Assembly	CDF-AEC-Q100-001	5 units / 1 lot	0/5	Pass	